

## SCOPE OF ACCREDITATION TO ISO/IEC 17025:2017

### SMT Corporation

14 High Bridge Road, Sandy Hook, CT 06482  
 Kimberly Costa 203 270 4700  
 kcosta@smtcorp.com www.smtcorp.com

In recognition of a successful assessment to ISO/IEC 17025:2017 General Requirements for the competence of Testing and Calibration Laboratories, AS6171 General Requirements, and the requirements of the ANAB SR 2429 – Labs Performing Detection of Suspect/Counterfeit Parts Under AS6171 program, accreditation is granted to the **SMT Corporation** to perform the following AS6171 slash sheet tests:

### TESTING

ISO/IEC 17025 Accreditation Granted: **22 October 2024**

Certificate Number: **AT-1733**

Certificate Expiry Date: **22 October 2026**

#### Non-Destructive

Specific Tests and/or Properties Measured	Specification, Standard, Method, or Test Technique	Items, Materials or Product Tested	Key Equipment or Technology
Radiographic Examination / Inspection / 3D Radiography	Internal Procedures: W750-34 W750-36 W750-46 IDEA-STD-1010 AS6081 AS6171/5	Electrical, Electronic and Electromechanical (EEE) Components	DAGE Quadra 5 Manual Radiography and Semi-Automatic Radiography
X-Ray Fluorescence (XRF)	Internal Procedures: W750-16 IDEA-STD-1010 AS6171/3	Electrical, Electronic and Electromechanical (EEE) Components	Fischer XDAL Spectrometer X-Ray Fluorescence (XRF) System
Visual Inspection	Internal Procedure: W750-18 IDEA-STD-1010 AS6081 AS6171/2	Electrical, Electronic and Electromechanical (EEE) Components	Keyence VHX-7000 Digital Microscope, Nikon D90 Camera, Dino-lite Camera
Fourier Transform Infrared Spectroscopy (FTIR)	Internal Procedures: W750-44 AS6171/9	Electrical, Electronic and Electromechanical (EEE) Components	Thermo Scientific Nicolet iS50 Fourier Transform Infrared Spectroscopy (FTIR) System



ANSI National Accreditation Board

**Non-Destructive**

Specific Tests and/or Properties Measured	Specification, Standard, Method, or Test Technique	Items, Materials or Product Tested	Key Equipment or Technology
RAMAN Spectroscopy	Internal Procedures: W750-39 AS6171/8	Electrical, Electronic and Electromechanical (EEE) Components	Thermo Scientific DXR3 RAMAN Spectroscopy (RAMAN) System

**Mechanical Testing**

Specific Tests and/or Properties Measured	Specification, Standard, Method, or Test Technique	Items, Materials or Product Tested	Key Equipment or Technology
Resistance to Solvents (RTS) / Scrape Test	Internal Procedure: W750-11 W750-13 IDEA-STD-1010 AS6081 AS6171/2	Electrical, Electronic and Electromechanical (EEE) Components	Hot Plate, X-Acto Number 11 blade, Cotton Swab, Solvents
Scanning Electron Microscopy (SEM) Examination / Inspection	Internal Procedure: W750-12 IDEA-STD-1010 AS6081 AS6171/2	Electrical, Electronic and Electromechanical (EEE) Components	Tescan Vega Variable Pressure SEM
Packaging Configuration and Dimensions	Internal Procedure: W750-19 MIL-STD-883 Method 2016 IDEA-STD-1010 AS6081 AS6171/2	Electrical, Electronic and Electromechanical (EEE) Components	Calipers Device to print Package Dimensions Non-Contact Measurement Tool
Solderability Test	Internal Procedures: W750-14 IDEA-STD-1010 J-STD-002 MIL-STD-883 MIL-STD-202 IEC 60068-2-20	Electrical, Electronic and Electromechanical (EEE) Components	GEN3 MUST3 Automated Force Wetting Solderability System
Dynasolve / 1-Methyl 2- Pyrrolidinone	Internal Procedure: W750-09 IDEA-STD-1010 AS6081 AS6171/2	Electrical, Electronic and Electromechanical (EEE) Components	Hot Plate, X-Acto Number 11 blade, Cotton Swab, Solvents



ANSI National Accreditation Board

**Mechanical Testing**

Specific Tests and/or Properties Measured	Specification, Standard, Method, or Test Technique	Items, Materials or Product Tested	Key Equipment or Technology
Decapsulation and Die Verification	Internal Procedure: W750-10 W750-21 IDEA-STD-1010 AS6081 AS6171/4	Electrical, Electronic and Electromechanical (EEE) Components	Nisene Jet-Etch Acid Decapsulator
Fine and Gross Leak Hermetic Seal	Internal Procedures: W800-1014 MIL-STD-750 METHOD 1071 MIL-STD-883 METHOD 1014 AS6171/7	Electrical, Electronic and Electromechanical (EEE) Components	Oneida Research Services HSHLD Model 310
Temperature Cycling	Internal Procedures: W800-1010 MIL-STD-883 METHOD 1010.9 MIL-STD-750 METHOD 1051.9 AS6171/7	Electrical, Electronic and Electromechanical (EEE) Components	ESPEC BTZ-4200
Particle Impact Noise Detection (PIND)	Internal Procedures: W883-2020 MIL-STD-750 METHOD 2052 MIL-STD-883 METHOD 2020	Electrical, Electronic and Electromechanical (EEE) Components	B&W Engineering BW-LPD- DAQ4000 Particle Impact Noise Detection System
Bond Pull Die Shear	Internal Procedures: W750-45 AS6171/4	Electrical, Electronic and Electromechanical (EEE) Components	Nordson Stellar 4000 Bondtest System
Constant Acceleration	Internal Procedures: W800-2001 MIL-STD-750 METHOD 2006 MIL-STD-883 METHOD 2001	Electrical, Electronic and Electromechanical (EEE) Components	Beckman-Coulter Avanti JXN-30 Centrifuge



ANSI National Accreditation Board

**Electrical**

Specific Tests and/or Properties Measured	Specification, Standard, Method, or Test Technique	Items, Materials or Product Tested	Key Equipment or Technology
Capacitance Measurement, Contact Resistance	MIL-STD-202 METHOD: 305A, 307 Internal Procedure: W750-03, W750-02 AS6171/7	Electrical, Electronic and Electromechanical (EEE) Components	LCR Meter – Quadtech 7600B Multimeter
Forward Voltage Drop, Reverse Current Leakage, Regulator (breakdown) Voltage	MIL-STD-750 METHOD: 4011, 4016, 4022 Internal procedure: W750-4011.4, 4016.4, 4022 AS6171/7	Diodes, Zener Diodes	PXI-4130 Source-Measure Unit, PXI-4072 DMM, PXIe-6556 Digital Waveform Generator
Propagation Delay, Power Supply Current	MIL-STD-883 METHOD: 3003, 3005 Internal procedure: W883-3003, 3005 AS6171/7	Microcircuits	PXI-4130 Source-Measure Unit, PXI-4072 DMM, PXI-4110 Power Supply, PXI-6556 Digital Waveform Generator, LeCroy WavePro 7300A 3GHz Oscilloscope,
High Level Output Voltage, Low Level Output Voltage, Input Clamp Voltage	MIL-STD-883 METHOD: 3006, 3007,3022 Internal procedure: W883-3006, 3007, 3022 AS6171/7	Microcircuits	PXI-4130 Source-Measure Unit PXI-4110 Power Supply PXI-4072 DMM
Low Level Input Current, High Level Input current, Output Short Circuit Current	MIL-STD-883 METHOD: 3009, 3010, 3011 Internal procedure: W883-3009, 3010, 3011	Microcircuits	PXI-4130 Source-Measure Unit PXI-4110 Power Supply PXI-4072 DMM
Functional Testing	MIL-STD-883 METHOD 3014, Internal procedure: W883-3014	Microcircuits	PXI-4110 Power Supply PXI-6556 Digital Waveform Generator
Burn-In	Internal Procedures: W883-1015, W750-1015 MIL-STD-883 METHOD 1015 MIL-STD-750 METHODS 1038.5, 1039.4, 1040, 1042.4 AS6171/7	Electrical, Electronic and Electromechanical (EEE) Components	ESPEC BTZ-4200 Various Electrical Testing Equipment

**SATELLITE SITE**

**SMT Labs UK Ltd.**

6 Stirling Park, Laker Road Rochester, Kent, ME1 3QR  
 United Kingdom  
 Kimberly Costa 203 270 4740  
 kcosta@smtcorp.com www.smtcorp.com

**TESTING**

**Non-Destructive**

Specific Tests and/or Properties Measured	Specification, Standard, Method, or Test Technique	Items, Materials or Product Tested	Key Equipment or Technology
Radiographic Examination / Inspection	Internal Procedures: W750-36 AS6171/5	Electrical, Electronic and Electromechanical (EEE) Components	Creative Electron Tru View Prime R, Manual Radiography and Semi-Automatic Radiography
X-Ray Fluorescence (XRF)	Internal Procedures: W750-16 AS6171/3	Electrical, Electronic and Electromechanical (EEE) Components	Fischer XDAL Spectrometer X-Ray Fluorescence (XRF) System
Visual Inspection	Internal Procedure: W750-18 AS6171/2	Electrical, Electronic and Electromechanical (EEE) Components	Keyence VHX-7000 Digital Microscope, Nikon D90 Camera, Dino-lite Camera

**Mechanical Testing**

Specific Tests and/or Properties Measured	Specification, Standard, Method, or Test Technique	Items, Materials or Product Tested	Key Equipment or Technology
Resistance to Solvents (RTS) / Scrape Test	Internal Procedure: W750-11 W750-13 AS6171/2	Electrical, Electronic and Electromechanical (EEE) Components	Hot Plate, X-Acto Number 11 blade, Cotton Swab, Solvents



**ANSI National Accreditation Board**

**Mechanical Testing**

<b>Specific Tests and/or Properties Measured</b>	<b>Specification, Standard, Method, or Test Technique</b>	<b>Items, Materials or Product Tested</b>	<b>Key Equipment or Technology</b>
Packaging Configuration and Dimensions	Internal Procedure: W750-19 AS6171/2	Electrical, Electronic and Electromechanical (EEE) Components	Calipers Device to print Package Dimensions Non-Contact Measurement Tool
Dynasolve / 1-Methyl 2- Pyrrolidinone	Internal Procedure: W750-09 AS6171/2	Electrical, Electronic and Electromechanical (EEE) Components	Hot Plate, X-Acto Number 11 blade, Cotton Swab, Solvents
Decapsulation and Die Verification	Internal Procedure: W750-10 W750-21 AS6171/4	Electrical, Electronic and Electromechanical (EEE) Components	Nisene Jet-Etch Acid Decapsulator

**Electrical**

<b>Specific Tests and/or Properties Measured</b>	<b>Specification, Standard, Method, or Test Technique</b>	<b>Items, Materials or Product Tested</b>	<b>Key Equipment or Technology</b>
Passive Component Testing	Internal Procedure: W750-50UK W750-51UK AS6171/7	Electrical, Electronic and Electromechanical (EEE) Components	LCR Meter Multimeter